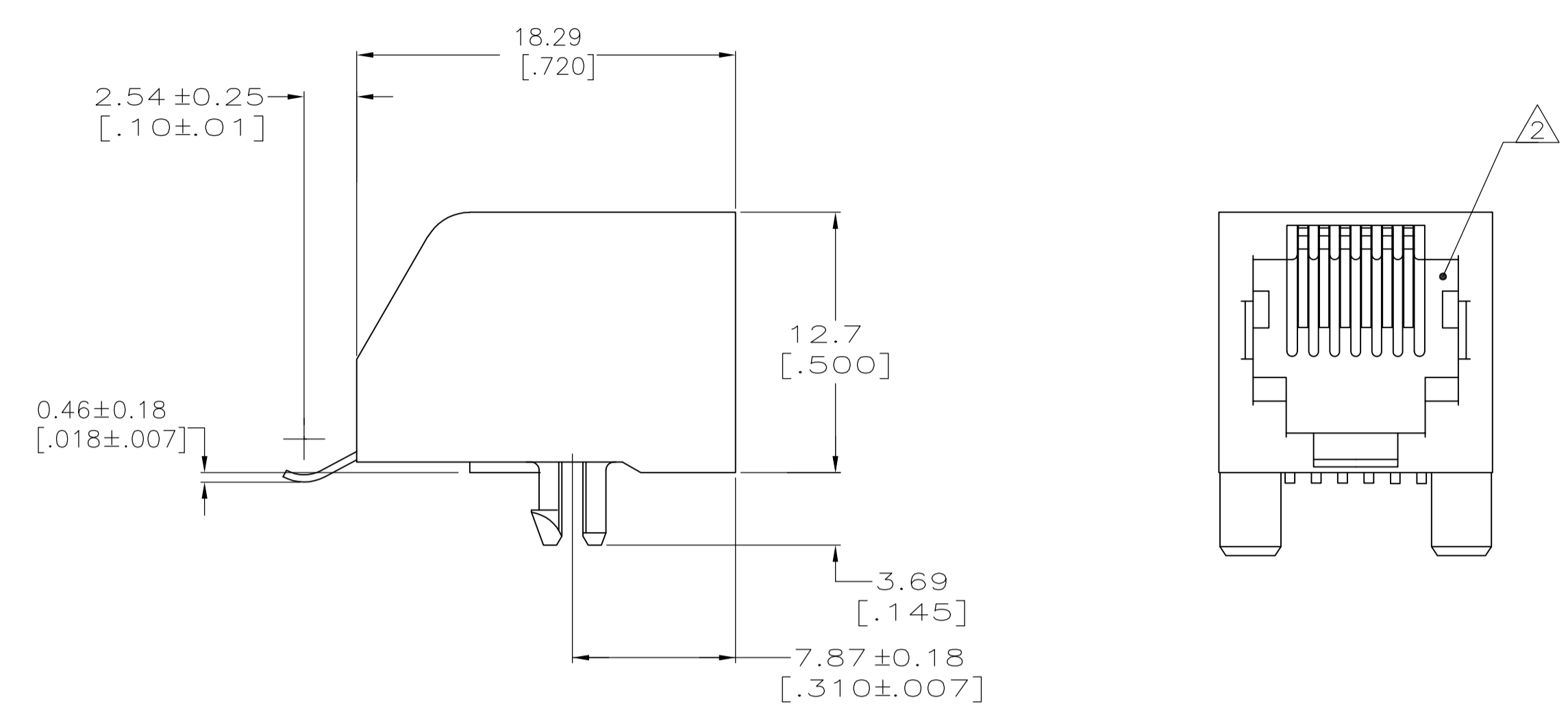
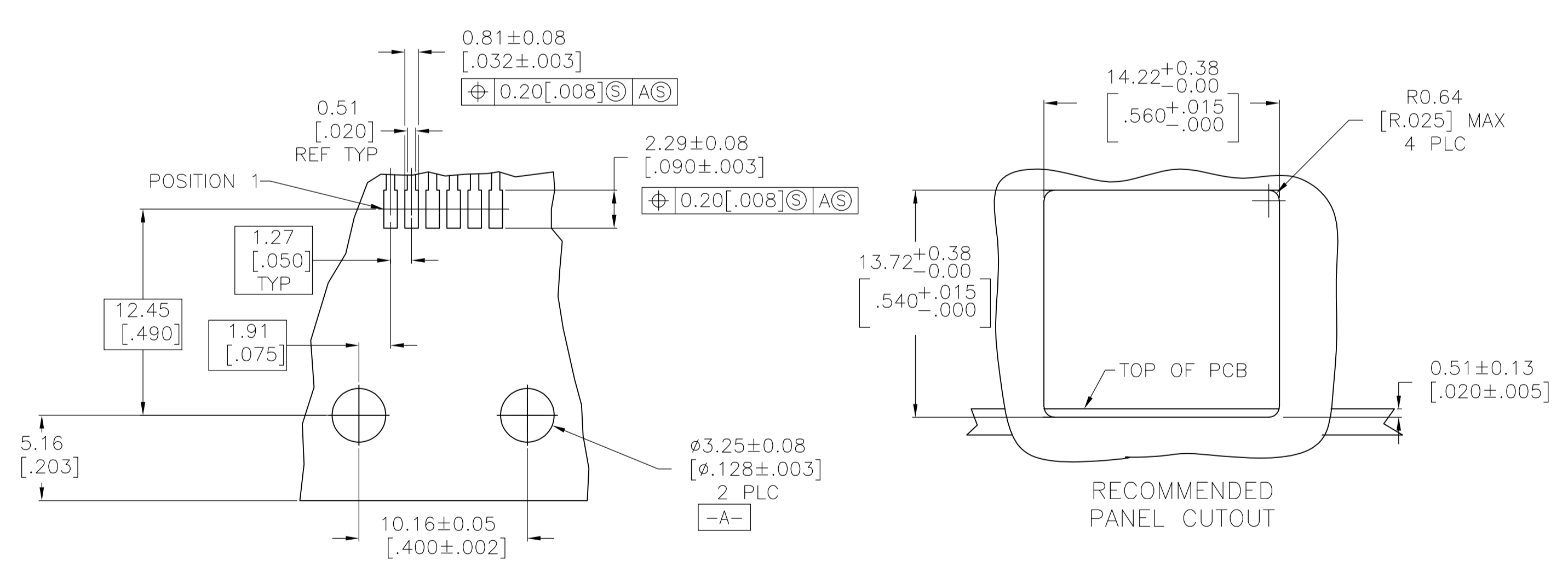
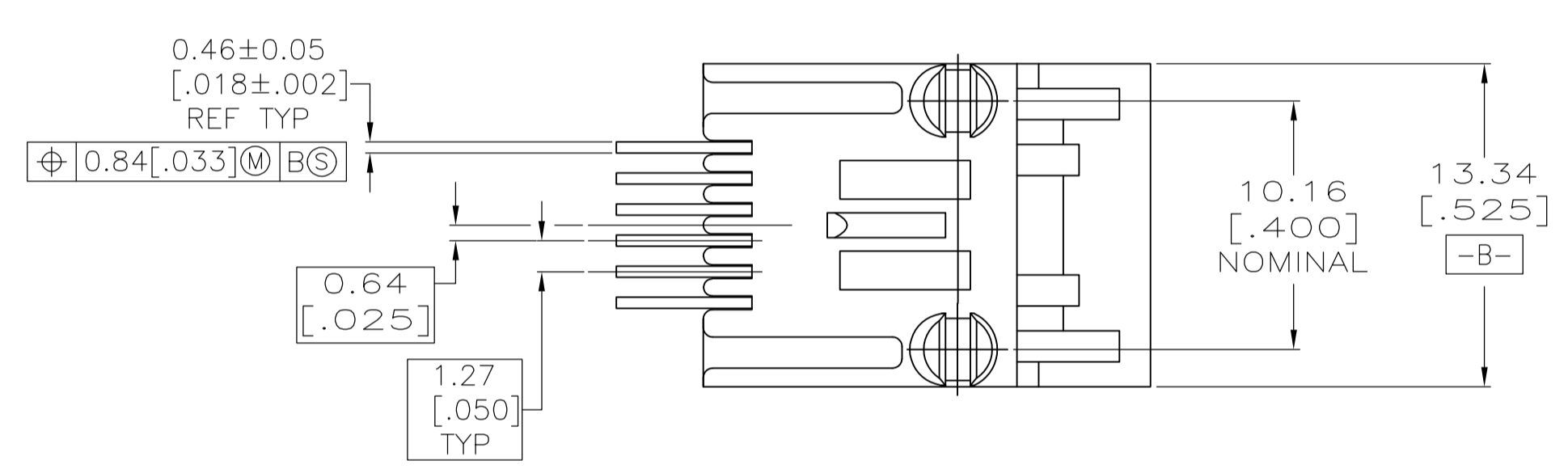


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DNW	APVD		
B1	REVISED PER	ECO-11-005033	23MAR11	RK	HMR		



- MATERIAL: HOUSING- HTN MOLDING COMPOUND, 94VO, COLOR: BLACK.
 TERMINAL- 0.36 [.014] THICK PHOS BRONZE PLATED WITH 1.27 μm [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [.000050] MIN THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SNAP-IN RETENTION FEATURE ACCOMMODATES A 1.57 ± 0.13 [.062 ± .005] PRINTED CIRCUIT BOARD.
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- TERMINALS SHALL BE ASSEMBLED IN CENTER POSITIONS FOR -2.
- 2 PACKAGED 42 ASSEMBLIES PER TUBE.



RECOMMENDED PRINTED CIRCUIT BOARD COMPONENT SIDE

RECOMMENDED PANEL CUTOUT

4	5557314-2
6	5557314-1 (SHOWN)
TERMINALS REQUIRED	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN L.A.MAYER 27AJG2007	NAME
0 PLC ± -	1 PLC ± -	CHK P.RECCCE 27AJG2007	APVD S.FLICKINGER 27AJG2007
2 PLC ± -	3 PLC ± -	PRODUCT SPEC	108-1163
4 PLC ± -	ANGLES ± -	APPLICATION SPEC	114-8040
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	SIZE
			A1 00779
		CUSTOMER DRAWING	SCALE 4:1 SHEET 1 OF 1 REV B1

STE TE Connectivity
 MODULAR JACK ASSEMBLY, 6 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT

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